

CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Previously Presented) A temperature control system for a semiconductor processing facility comprising:

a cooling unit for controlling the temperature of a cooling fluid wherein said cooling unit is a refrigeration unit that provides compressed refrigerant; and

a plurality of remote temperature control modules in fluid communication with said cooling unit, each of said remote temperature control modules including:

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module, said cooling fluid circulation loop being in fluid communication with said cooling unit;

a heat transfer fluid circulation loop for circulating a heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with at least one process component of said semiconductor processing facility;

an integrated heat exchanger including a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and an electrical heat source, the integrated heat exchanger exchanging heat between said cooling fluid that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation

loop, said electrical heat source being in thermal communication with a portion of said cooling fluid circulation loop and a portion of said heat transfer fluid circulation loop;

a current controller being operably coupled with said electrical heat source;

a cooling fluid control valve in fluid communication with said cooling fluid circulation loop for controlling the circulation of said cooling fluid through said cooling fluid circulation loop; and

a controller programmed with a temperature control logic for controlling said cooling fluid control valve and controlling said current controller.

2. (Previously Presented) The temperature control system of claim 1 wherein each of said remote temperature control modules includes the heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

3. (Previously Presented) The temperature control system of claim 2 wherein said heat source is controlled by said temperature control logic in response to temperature set point information and temperature feedback information related to said process component.

4. (Cancelled)

5. (Cancelled)

6. (Original) The temperature control system of claim 1 wherein said cooling unit is physically separate from said plurality of remote temperature control modules.

7. (Original) The temperature control system of claim 6 wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

8. (Original) The temperature control system of claim 7 wherein said plurality of remote temperature control modules are located in a subfloor area of said semiconductor processing facility.

9. (Original) The temperature control system of claim 7 wherein said plurality of remote temperature control modules are physically connected to process tools within said semiconductor processing facility.

10. (Previously Presented) The temperature control system of claim 1 wherein each of said at least one process components has a set point temperature where said cooling unit is set to maintain said cooling fluid at a temperature correlating to a lowest temperature among all of said at least one process components that are thermally influenced by said cooling fluid.

11. (Previously Presented) The temperature control system of claim 1 wherein said cooling unit provides the compressed refrigerant to said plurality of remote temperature control modules.

12. (Original) The temperature control system of claim 11 wherein:
said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control module;

said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and

further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.

13. (Original) The temperature control valve of claim 12 wherein each of said remote temperature control modules includes a heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

14. (Previously Presented) A temperature control system for a process component of a semiconductor processing facility comprising:

at least one remote temperature control module, said remote temperature control module including:

a cooling fluid input for receiving cooling fluid from a cooling unit that serves multiple remote temperature control modules where said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a refrigeration unit;

a cooling fluid output for returning cooling fluid to said cooling unit that serves multiple remote temperature control modules;

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process component;

a heat transfer fluid output for returning said heat transfer fluid to said process component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with said process component of said semiconductor processing facility;

an integrated heat exchanger including a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and an electrical heat source, the integrated heat exchanger exchanging heat between said cooling fluid that is circulated in said cooling fluid

circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop, said electrical heat source being in thermal communication with a portion of said cooling fluid circulation loop and said heat transfer fluid circulation loop;

a current controller being operably coupled with said electrical heat source;

a cooling fluid control valve in fluid communication with said cooling fluid circulation loop for controlling the circulation of said cooling fluid through said cooling fluid circulation loop; and

a controller programmed with a temperature control logic for controlling said cooling fluid control valve and controlling said current controller.

15. (Previously Presented) The temperature control system of claim 14 wherein said remote temperature control module includes a the heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

16. (Previously Presented) The temperature control system of claim 15 wherein said heat source is controlled by said temperature control logic in response to temperature set point information and temperature feedback information related to said process component.

17. (Cancelled)

18. (Cancelled)

19. (Previously Presented) The temperature control system of claim 14 wherein said cooling unit is physically separate from said remote temperature control module and said multiple remote temperature control modules.

20. (Original) The temperature control system of claim 14 wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

21. (Original) The temperature control system of claim 19 wherein said remote temperature control module is located in a subfloor area of said semiconductor processing facility.

22. (Original) The temperature control system of claim 19 wherein said remote temperature control module is physically connected to a process tool within said semiconductor processing facility.

23. (Previously Presented) The temperature control system of claim 14 wherein said cooling unit is set to maintain said cooling fluid at a temperature correlating to a lowest temperature among all of said at least one remote temperature control modules that are served by said cooling unit.

24. (Previously Presented) The temperature control system of claim 14 wherein:
the refrigeration unit serves multiple remote temperature control modules;

said cooling fluid output is a refrigerant output for returning expanded refrigerant to said refrigeration unit that serves multiple remote temperature control modules;

said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control modules;

said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and

further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.

25. (Previously Presented) A temperature control system for a process component of a semiconductor processing facility comprising:

at least one remote temperature control module, said remote temperature control module including:

a cooling fluid input for receiving cooling fluid from a physically separate cooling unit that serves multiple remote temperature control modules where said cooling fluid input is a refrigerant input for receiving compressed refrigerant from a refrigeration unit;

a cooling fluid output for returning cooling fluid to said cooling unit that serves multiple remote temperature control modules;

a cooling fluid circulation loop for circulating said cooling fluid through said remote temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process component;

a heat transfer fluid output for returning said heat transfer fluid to said process component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with said process component of said semiconductor processing facility, wherein said cooling fluid circulation and said heat transfer fluid circulation loop are separate fluid distribution systems;

an electrical heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid;

an integrated heat exchanger for exchanging heat between said cooling fluid that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and the electrical heat source, said electrical heat source being in thermal communication with the portion of the cooling fluid loop and the portion of the heat transfer fluid circulation loop;

a current controller being operably coupled to said electrical heat source;

a cooling fluid control valve in fluid communication with said cooling fluid circulation loop for controlling the circulation of said cooling fluid through said cooling fluid circulation loop; and

a controller programmed with a temperature control logic for controlling said cooling fluid control valve and said electrical heat source.

26. (Cancelled)

27. (Original) The temperature control system of claim 25 wherein said cooling unit is located in a utility basement of said semiconductor processing facility.

28. (Original) The temperature control system of claim 27 wherein said remote temperature control module is located in a subfloor area of said semiconductor processing facility.

29. (Previously Presented) The temperature control system of claim 25 wherein said cooling unit is set to maintain said cooling fluid at a temperature correlating to a lowest temperature among all of said at least one remote temperature control modules that are served by said cooling unit.

30. (Previously Presented) The temperature control system of claim 25 wherein:
- said refrigeration unit serves multiple remote temperature control modules;
 - said cooling fluid output is a refrigerant output for returning expanded refrigerant to said refrigeration unit that serves multiple remote temperature control modules;
 - said cooling fluid circulation loop is a refrigerant circulation loop for circulating refrigerant through said remote temperature control modules;
 - said cooling fluid control valve is a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop; and
 - further including a flow control valve for controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve.
31. (Previously Presented) A temperature control system for a semiconductor processing facility comprising:
- a refrigeration unit for providing a compressed refrigerant; and
 - a plurality of remote temperature control modules in fluid communication with said refrigeration unit, each of said remote temperature control modules including:
 - a refrigerant circulation loop for circulating said refrigerant through said remote temperature control module, said refrigerant circulation loop being in fluid communication with said refrigeration unit;
 - a heat transfer fluid circulation loop for circulating a heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with a process component of said semiconductor processing facility;

a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop;

a flow control valve in fluid communication with said refrigerant circulation loop for controlling the circulation of said refrigerant through said refrigerant circulation loop; said flow control valve being downstream from said thermal expansion valve;

an integrated heat exchanger for exchanging heat between said refrigerant that is circulated in said cooling fluid circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and an electrical heat source, said electrical heat source being in thermal communication with the portion of the cooling fluid loop and the portion of the heat transfer fluid circulation loop;

a current controller being operably coupled to said electrical heat source; and

a controller programmed with a temperature control logic for controlling said cooling fluid control valve and controlling said current controller.

32. (Previously Presented) The temperature control system of claim 31 wherein each of said remote temperature control modules includes the heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.

33. (Previously Presented) A temperature control system for a process component of a semiconductor processing facility comprising:

at least one remote temperature control module, said remote temperature control module including:

a refrigerant input for receiving compressed refrigerant from a refrigeration unit that serves multiple remote temperature control modules;

a refrigerant output for returning expanded refrigerant to said refrigeration unit that serves multiple remote temperature control modules;

a refrigerant circulation loop for circulating said refrigerant through said remote temperature control module;

a heat transfer fluid input for receiving heat transfer fluid from said process component;

a heat transfer fluid output for returning said heat transfer fluid to said process component;

a heat transfer fluid circulation loop for circulating said heat transfer fluid through said remote temperature control module, said heat transfer fluid being in fluid communication with said process component of said semiconductor processing facility;

a thermal expansion valve for controlling the circulation of said refrigerant through said refrigerant circulation loop;

a flow control valve for in fluid communication with said refrigerant circulation loop controlling the circulation of said refrigerant through said refrigerant circulation loop, said flow control valve being downstream from said thermal expansion valve;

an integrated heat exchanger for exchanging heat between said refrigerant that is circulated in said refrigerant circulation loop and said heat transfer fluid that is circulated in said heat transfer fluid circulation loop where the integrated heat exchanger includes a portion of the cooling fluid circulation loop, a portion of the heat transfer fluid circulation loop and the an electrical heat source, said electrical heat source being in thermal communication with a portion of said cooling fluid circulation loop and said heat transfer fluid circulation loop;

a current controller being operably coupled with said electrical heat source; and

a controller programmed with a temperature control logic for controlling said cooling fluid control valve and controlling said current controller.

34. (Previously Presented) The temperature control system of claim 33 wherein said remote temperature control module includes the heat source in thermal communication with said heat transfer fluid for providing heat to said heat transfer fluid.